Single 2-Input AND Gate

The NL17SV08 is an ultra–high performance 2–Input AND gate manufactured in 0.35μ CMOS technology with excellent performance down to 0.9 volts. This device is ideal for extremely high–speed and high–drive applications. Additionally, limitations of board space are no longer a constraint. The very small SOT–553 makes this device fit most tight designs and spaces.

Features

- Extremely High Speed: $t_{PD} = 1.0 \text{ ns (Typ)} @ V_{CC} = 3.3 \text{ V}$
- Designed for 0.9 to 3.3 V Operation
- Overvoltage Tolerance (OVT)* Input Pins Permit Logic Translation
- Balanced ±24 mA Output Drive @ 3.3 V
- Near Zero Static Supply Current
- Ultra-Tiny SOT-553 5 Pin Package Only 1.6 x 1.6 x 0.6 mm
- All Devices in Package SOT-553 are Inherently Pb-Free

Typical Applications

- Cellular
- Digital Camera
- PDA
- Digital Video

Industry Standard

• Functionally Similar to NC7SV08 and SN74AUC1G08



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MARKING DIAGRAM



SOT-553 CASE 463B



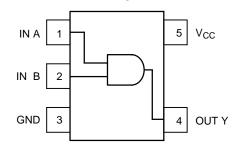
UG = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

PIN DIAGRAM



PIN ASSIGNMENT

PIN#	FUNCTION
1	IN A
2	IN B
3	GND
4	OUT Y
5	V _{CC}

FUNCTION TABLE

Input A	Input B	Output Y
L	L	L
L	Н	L
н	L	L
Н	Н	Н

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

^{*}Overvoltage Tolerance (OVT) enables input pins to function outside (higher) of their operating voltages, with no damage to the devices or to signal integrity.

MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to + 4.6	V
VI	DC Input Voltage	-0.5 to + 4.6	V
Vo	DC Output Voltage	-0.5 to V _{CC} +0.5	V
I _{IK}	DC Input Diode Current V _I < GN	ID ±50	mA
I _{OK}	DC Output Diode Current $V_O = GN$ $V_O = V_O$		mA
Io	DC Output Sink Current	±50	mA
I _{CC}	DC Supply Current per Supply Pin	±50	mA
I _{GND}	DC Ground Current per Ground Pin	±50	mA
T _{STG}	Storage Temperature Range	- 65 to +150	°C
TL	Lead Temperature, 1.0 mm from Case for 10 seconds	260	°C
TJ	Junction Temperature Under Bias	+150	°C
$\theta_{\sf JA}$	Thermal Resistance (Note 1)	250	°C/W
P _D	Power Dissipation in Still Air at 85°C	250	mW
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 3	34 UL 94 V–0 @ 0.125 in	

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Paramet	er	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage		0.9	3.6	V
V _{IN}	Digital Input Voltage		0	3.6	V
V _{out}	Output Voltage		0	V _{CC}	V
I _{OH} /I _{OL}	Output Current	$\begin{array}{c} V_{CC} = 3.0 \text{ V to } 3.6 \text{ V} \\ V_{CC} = 2.3 \text{ V to } 2.7 \text{ V} \\ V_{CC} = 1.65 \text{ V to } 1.95 \text{ V} \\ V_{CC} = 1.4 \text{ V to } 1.6 \text{ V} \\ V_{CC} = 1.1 \text{ V to } 1.3 \text{ V} \\ V_{CC} = 0.9 \text{ V} \end{array}$		±24 ±18 ±6 ±4 ±2 ±0.1	mA
t _A	Operating Temperature Range. All Pac	kage Types	-40	+85	°C
t _r , t _f	Input Rise or Fall Time	$V_{CC} = 3.3V \pm 0.3 V$	0	10	nS/V

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

^{1.} Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

DC CHARACTERISTICS- Digital Section (Voltages Referenced to GND)

				T _A = 25°C		$T_A = -40$	to 85°C	
Symbol	Parameter	Condition	V _{CC}	Min	Max	Min	Max	Unit
V_{IH}	High Level		0.90	0.65 x V _{CC}		0.65 x V _{CC}		V
	Input Voltage		$1.10 \le = V_{CC} \le 1.30$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.40 \le V_{CC} \le 1.60$	0.65 x V _{CC}		0.65 x V _{CC}		
			$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$	0.65 x V _{CC} 1.6		0.65 x V _{CC} 1.6		
			$2.70 \le V_{CC} \le 3.60$	2.0		2.0		
V _{IL}	Low Level		0.90		0.35 x V _{CC}		0.35 x V _{CC}	V
	Input Voltage		$1.10 \le V_{CC} \le 1.30$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.40 \le V_{CC} \le 1.60$		0.35 x V _{CC}		0.35 x V _{CC}	
			$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$		0.35 x V _{CC} 0.7		0.35 x V _{CC} 0.7	
			$2.70 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$		0.7		0.7	
V _{OH}	High Level	I _{OH} = -100 μA	0.90	V _{CC} - 0.1		V _{CC} – 0.1		V
	Output Voltage		$1.10 \le V_{CC} \le 1.30$	V _{CC} - 0.1		V _{CC} - 0.1		
			$1.40 \le V_{CC} \le 1.60$	V _{CC} – 0.2		$V_{CC} - 0.2$		
			$1.65 \le V_{CC} \le 1.95$	V _{CC} - 0.2		V _{CC} - 0.2		
			$2.30 \le V_{CC} \le 2.70$	V _{CC} - 0.2		V _{CC} - 0.2		
			$2.70 \le V_{CC} \le 3.60$	V _{CC} - 0.2		V _{CC} - 0.2		
		I _{OH} = -2.0 mA	$1.10 \le V_{CC} \le 1.30$	0.75 x V _{CC}		0.75 x V _{CC}		
		I _{OH} = -4.0 mA	$1.40 \le V_{CC} \le 1.60$	0.75 x V _{CC}		0.75 x V _{CC}		
		$I_{OH} = -6.0 \text{ mA}$	$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$	1.25 2.0		1.25 2.0		
		I _{OH} = -12 mA	$2.30 \le V_{CC} \le 2.70$	1.8		1.8		
			$2.70 \le V_{CC} \le 3.60$	2.2		2.2		
		I _{OH} = -18 mA	$2.30 \le V_{CC} \le 2.70$	1.7		1.7		
			$2.70 \le V_{CC} \le 3.60$	2.4		2.4		
		$I_{OH} = -24 \text{ mA}$	$2.70 \le V_{CC} \le 3.60$	2.2		2.2		
V_{OL}	Low Level Output Voltage	I_{OL} = 100 μ A	0.90		0.1		0.1	V
	Output voltage		$1.10 \le V_{CC} \le 1.30$		0.1		0.1	
			$1.40 \le V_{CC} \le 1.60$ $1.65 \le V_{CC} \le 1.95$		0.2 0.2		0.2 0.2	
			$2.30 \le V_{CC} \le 1.93$ $2.70 \le V_{CC} \le 1.93$		0.2		0.2	
			$2.70 \le V_{CC} \le 3.60$		0.2		0.2	
		I _{OL} = 2.0 mA	$1.10 \le V_{CC} \le 1.30$		0.25 x V _{CC}		0.25 x V _{CC}	
		I _{OL} = 4.0 mA	$1.40 \le V_{CC} \le 1.60$		0.25 x V _{CC}		0.25 x V _{CC}	
		$I_{OL} = 6.0 \text{ mA}$	$1.65 \le V_{CC} \le 1.95$		0.3		0.3	
		I _{OL} = 12 mA	$2.30 \le V_{CC} \le 2.70$		0.4		0.4	
			$2.70 \le V_{CC} \le 3.60$		0.4		0.4	
		I _{OL} = 18 mA	$2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$		0.6 0.4		0.6 0.4	
		I _{OL} = 24 mA	$2.70 \le V_{CC} \le 3.60$ $2.70 \le V_{CC} \le 3.60$		0.55		0.55	
I _{IN}	Input	$0 = V_1 = 3.6 \text{ V}$	0.90 to 3.60		±0.1		±0.9	μΑ
.114	Leakage Current	3 1 = 0.0 1					_5.5	Por .
l _{OFF}	Power Off Leakage Current		0		10		10	μΑ
I _{CC}	Quiescent Supply Current	$V_I = V_{CC}$ or GND	0.90 to 3.60		0.9		5	μΑ

AC CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ nS}$)

		-40°C			25°C			85°C	
Symbol	Parameter	Condition	V _{CC}	Min	Тур	Max	Min	Max	Unit
T _{PHL,}	Propagation Delay	$C_L = 15 \text{ pF}, R_L = 1.0 \text{ M}\Omega$	0.90		13				nS
T _{PLH}		$C_L = 15 \text{ pF}, R_L = 2.0 \text{ k}\Omega$	$1.10 \le V_{CC} \le 1.30$ $1.40 \le V_{CC} \le 1.60$	3.0 1.0	6.0 3.2	10.0 6.0	1.0 1.0	14.6 7.2	nS
		$C_L = 30 \text{ pF}, R_L = 500 \text{ k}\Omega$	$1.65 \le V_{CC} \le 1.95$ $2.30 \le V_{CC} \le 2.70$ $2.70 \le V_{CC} \le 3.60$	1.0 0.8 0.7	2.0 1.2 1.0	4.5 2.6 2.3	1.0 0.7 0.6	5.3 3.7 3.0	nS
C _{IN}	Input Capacitance		0		2.0				pF
C _{OUT}	Output Capacitance		0		4.5				pF
C _{PD}	Power Dissipation Capacitance	$V_I = 0 \text{ V or } V_{CC}$ $F = 10 \text{ MHz}$	0.90 to 3.60		20				pF

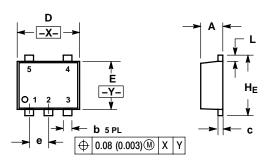
ORDERING INFORMATION

Device Order Number	Package Type	Shipping [†]
NL17SV08XV5T2	SOT-553*	178 mm, 4000 Units / Tape & Reel
NL17SV08XV5T2G	SOT-553*	178 mm, 4000 Units / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb–Free.

PACKAGE DIMENSIONS

SOT-553 5-LEAD PACKAGE CASE 463B-01 ISSUE B

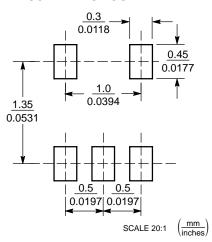


NOTES

- DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX
Α	0.50	0.55	0.60	0.020	0.022	0.024
b	0.17	0.22	0.27	0.007	0.009	0.011
С	0.08	0.13	0.18	0.003	0.005	0.007
D	1.50	1.60	1.70	0.059	0.063	0.067
E	1.10	1.20	1.30	0.043	0.047	0.051
е		0.50 BSC			0.020 BSC	
L	0.10	0.20	0.30	0.004	0.008	0.012
HE	1.50	1.60	1.70	0.059	0.063	0.067

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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